

# 10V Drive Nch MOSFET

## **R6012FNX**

#### Structure

Silicon N-channel MOSFET

#### Features

- 1) Fast reverse recovery time (t<sub>rr</sub>)
- 2) Low on-resistance.
- 3) Fast switching speed.
- 4) Gate-source voltage  $V_{GSS}$  garanteed to be  $\pm 30V$ .
- 5) Drive circuits can be simple.
- 6) Parallel use is easy.

# Application

Switching

#### Packaging specifications

	Package	Bulk	
Type	Code	-	
	Basic ordering unit (pieces)	500	
R6012FNX		0	

# ● Absolute maximum ratings (Ta = 25°C)

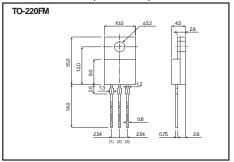
Paramet	Symbol	Limits	Unit	
Drain-source voltage		$V_{DSS}$	600	V
Gate-source voltage		$V_{GSS}$	±30	V
Drain current	Continuous	I <sub>D</sub> *3	±12	Α
Dialii Cuiteili	Pulsed	I <sub>DP</sub> *1	±48	Α
Source current (Body Diode)	Continuous	l <sub>S</sub> *3	12	Α
	Pulsed	I <sub>SP</sub> *1	48	Α
Avalanche Current		I <sub>AS</sub> *2	6	Α
Avalanche Energy		E <sub>AS</sub> *2	9.6	mJ
Power dissipation (Tc=25°C)		$P_D$	50	W
Channel temperature		Tch	150	°C
Range of storage temperature		Tstg	-55 to +150	°C

<sup>\*1</sup> Pw≤10µs, Duty cycle≤1%

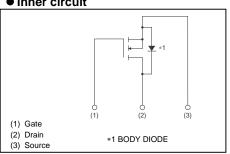
#### Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to Case	Rth (ch-c)	2.5	°C/W

#### • Dimensions (Unit : mm)



#### • Inner circuit



<sup>\*2</sup> L $\doteqdot$ 500 $\mu$ H, V<sub>DD</sub>=50V, Rg=25 $\Omega$ ,starting Tch=25°C

<sup>\*3</sup> Limited only by maximum temperature allowed.

# ● Electrical characteristics (Ta = 25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	$I_{GSS}$		-	±100	nΑ	$V_{GS}=\pm30V$ , $V_{DS}=0V$
Drain-source breakdown voltage	$V_{(BR)DSS}$	600	-	-	V	I <sub>D</sub> =1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	1	-	100	μΑ	V <sub>DS</sub> =600V, V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS (th)</sub>	3	-	5	V	$V_{DS}$ =10V, $I_{D}$ =1mA
Static drain-source on-state resistance	R <sub>DS (on)</sub> *	-	0.39	0.51	Ω	I <sub>D</sub> =6A, V <sub>GS</sub> =10V
Forward transfer admittance	I Y <sub>fs</sub> I*	3.5	1	-	S	I <sub>D</sub> =6A, V <sub>DS</sub> =10V
Input capacitance	C <sub>iss</sub>	ı	1300	1	рF	V <sub>DS</sub> =25V
Output capacitance	C <sub>oss</sub>	1	890	-	рF	V <sub>GS</sub> =0V
Reverse transfer capacitance	C <sub>rss</sub>	1	45	-	pF	f=1MHz
Turn-on delay time	t <sub>d(on)</sub> *	1	30	-	ns	I <sub>D</sub> =6A, V <sub>DD</sub> ≒300V
Rise time	t <sub>r</sub> *	1	37	-	ns	V <sub>GS</sub> =10V
Turn-off delay time	t <sub>d(off)</sub> *		77	-	ns	$R_L=50\Omega$
Fall time	t <sub>f</sub> *	-	20	-	ns	$R_G=10\Omega$
Total gate charge	Q <sub>g</sub> *	-	35	-	nC	I <sub>D</sub> =12A,
Gate-source charge	Q <sub>gs</sub> *	ı	10	-	nC	V <sub>DD</sub> ≒300V
Gate-drain charge	Q <sub>gd</sub> *	-	15	-	nC	V <sub>GS</sub> =10V

<sup>\*</sup>Pulsed

# ●Body diode characteristics (Source-Drain) (Ta = 25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward Voltage	V <sub>SD</sub> *	-	-	1.5	V	I <sub>s</sub> =12A, V <sub>GS</sub> =0V
Reverse Recovery Time	t <sub>rr</sub> *	45	75	105	ns	I <sub>s</sub> =12A, di/dt=100A/μs

<sup>\*</sup>Pulsed

# ●Electrical characteristic curves (Ta=25°C)

T<sub>a</sub>=25°C Pulsed V<sub>GS</sub>=10.0V V<sub>GS</sub>=8.0V V<sub>GS</sub>=6.5V V<sub>GS</sub>=6.5V V<sub>GS</sub>=5.5V V<sub>GS</sub>=5.5V

Fig.1 Typical Output Characteristics ( I )

Fig.3 Typical Transfer Characteristics

Drain-Source Voltage :  $V_{\rm DS}$  [V]

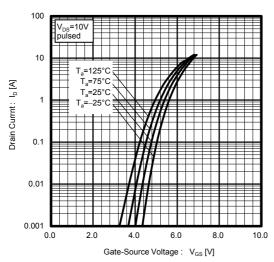


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

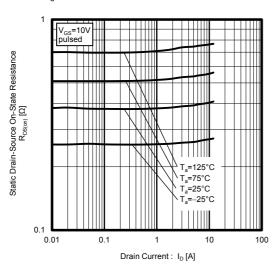


Fig.2 Typical Output Characteristics (  ${\rm I\hspace{-.1em}I}$  )

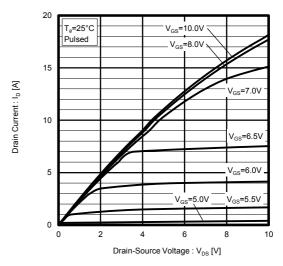


Fig.4 Gate Threshold Voltage vs. Channel Temperature

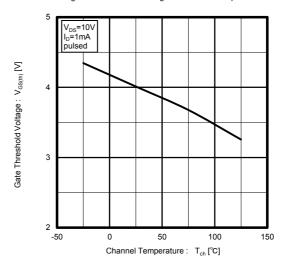


Fig.6 Static Drain-Source On-State Resistance vs. Channel Temperature

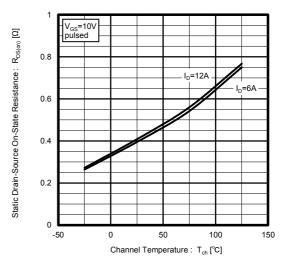


Fig.7 Forward Transfer Admittance vs. Drain Current

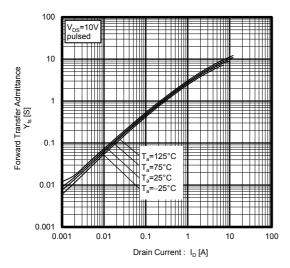


Fig.9 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

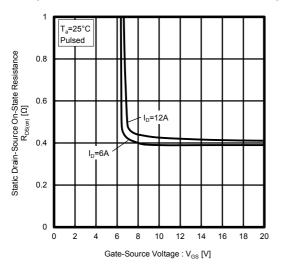


Fig.11 Dynamic Input Characteristics

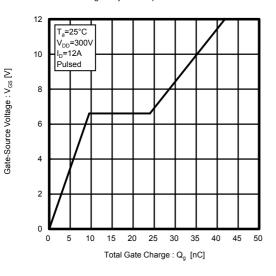


Fig.8 Source Current vs. Source-Drain Voltage

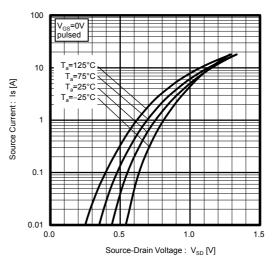


Fig.10 Switching Characteristics

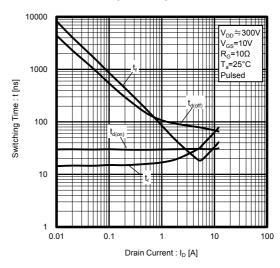


Fig.12 Typical Capacitance vs. Drain-Source Voltage

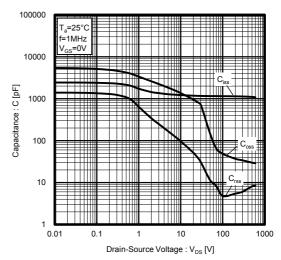


Fig.13 Reverse Recovery Time vs. Source Current

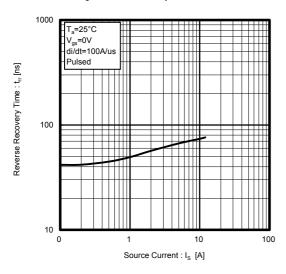


Fig.15 Normalized Transient Thermal Resistance v.s. Pulse Width

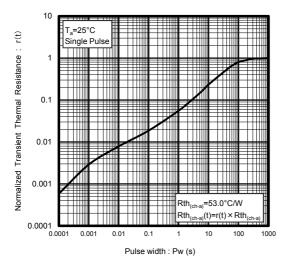
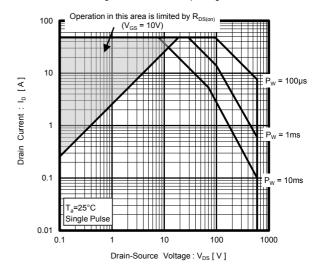


Fig.14 Maximum Safe Operating Area



## Measurement circuits

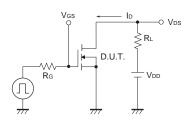


Fig.1-1 Switching Time Measurement Circuit

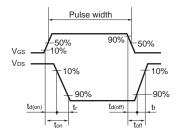


Fig.1-2 Switching Waveforms

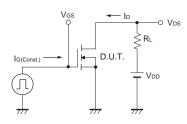


Fig.2-1 Gate Charge Measurement Circuit

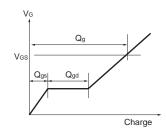


Fig.2-2 Gate Charge Waveform

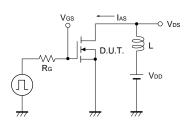


Fig.3-1 Avalanche Measurement Circuit

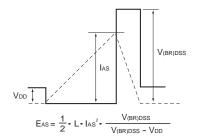


Fig.3-2 Avalanche Waveform

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